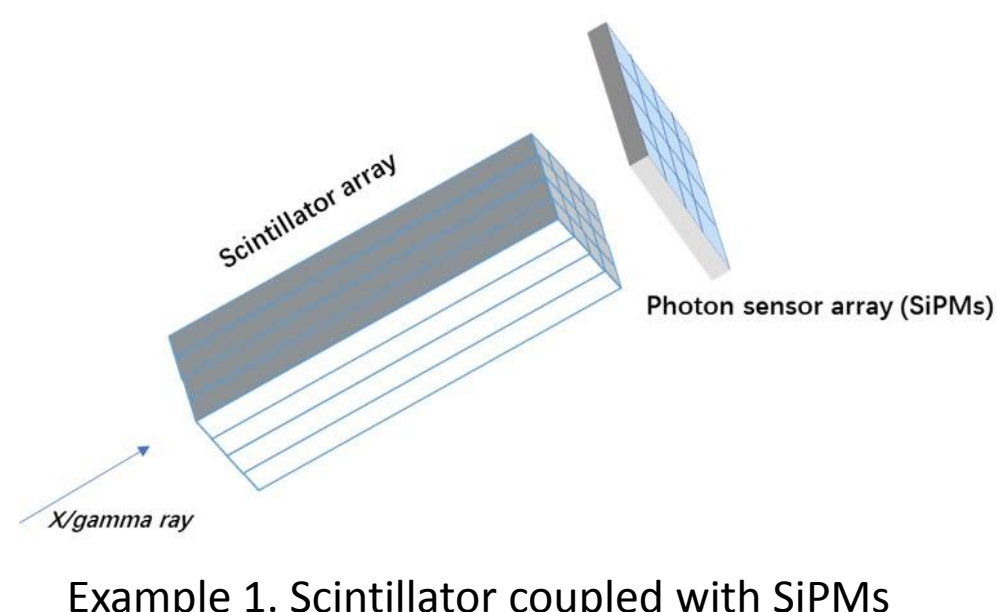
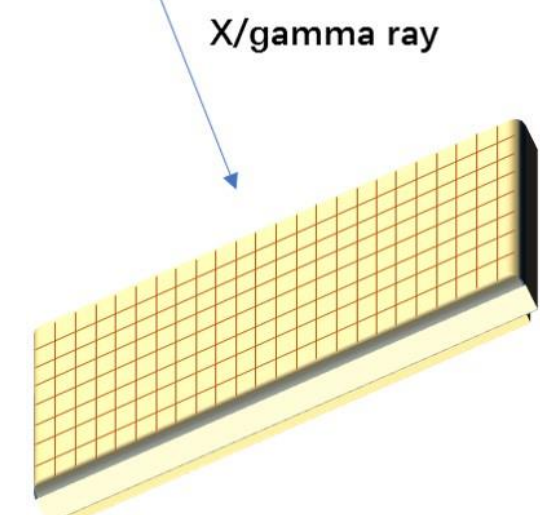


Research context and motivation

- X and gamma rays are photons with higher energy, shorter wavelength, stronger penetration ability than the Ultraviolet and Visible light.
- X and gamma rays detection plays important role in fields like nuclear physics, medical diagnosis, astronomy observation, radiation detect...
- Penetrating radiation inevitably faces the challenge of improving the detection efficiency.
- Technological schemes for X or gamma ray detection can be mainly categorized as : Scintillator + conventional photon detector and high Z (atomic number) semiconductor.
- Applied Specific Integrated Circuits (ASICs) need to work closely to detectors to read out the signal with expected goals: count rate, timing or spatial resolution, power dissipation, robustness for work environment.



Example 1. Scintillator coupled with SiPMs



Example 2. High Z semiconductor detector (CdZnTe)

Addressed research questions/problems

- Develop read out ASICs for SiPMs and CdZnTe detectors for high resolution X/gamma ray detection
- SiPMs readout requires very high time resolution, aimed sensors provided by FBK (Fondazione Bruno Kessler), with the expectations and challenges:



- SNR > 10, jitter < 1ns for 1 pe (1 cm² SiPM)
- Dark count rejection
- Working temperature at 77 K and 300 K
- Adjustable gain and threshold per channel
- Read out both positive and negative signals
- Radiation tolerance

- CdZnTe detectors read out for gamma cameras, in collaboration with IHEP (Institute of High Energy Physics, China), requires very low noise and good time resolution, with the expectations and challenges:



- Channels: 121 (for anode) + 2 (for cathode)
- Input range: ~100 fC
- Count rate > 10k per channel
- ENC < 100e (Cd = 2 pF)
- Adjustable shaping time and gain
- Radiation tolerance

Adopted methodologies

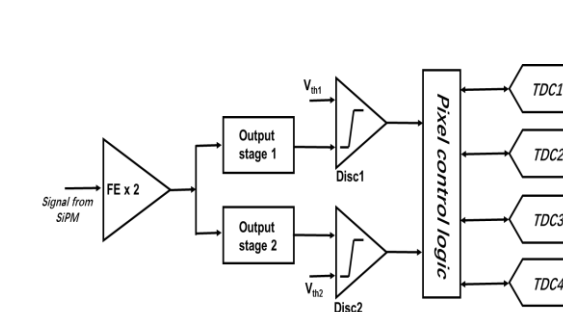
- UMC 110 nm CMOS process
- Cadence IC design and simulation tools
- Test blocks of Very Front End (VFE) and basic digital modules to study their behavior at cryogenic temperature

Submitted and published works

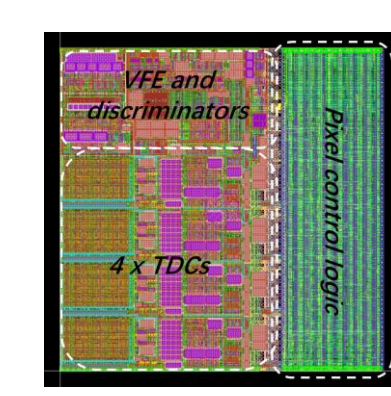
- CHENG, Weishuai. "A Versatile Mixed-Signal Large Dynamic Range Front-End ASIC for High Capacitance Detectors." 2019 15th Conference on Ph. D Research in Microelectronics and Electronics (PRIME). IEEE, 2019.
- Cheng, W., et al. "A mixed-signal large dynamic range front-end ASIC for high capacitance detectors." Journal of Instrumentation 14.08 (2019): P08013.
- Rivetti, A., Alexeev, M., Bugalho, R., Cossio, F., Rolo, M.D.R., Di Francesco, A., Greco, M., Cheng, W., Maggiora, M., Marcello, S. and Mignone, M., 2019. TIGER: A front-end ASIC for timing and energy measurements with radiation detectors. Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment.

Novel contributions

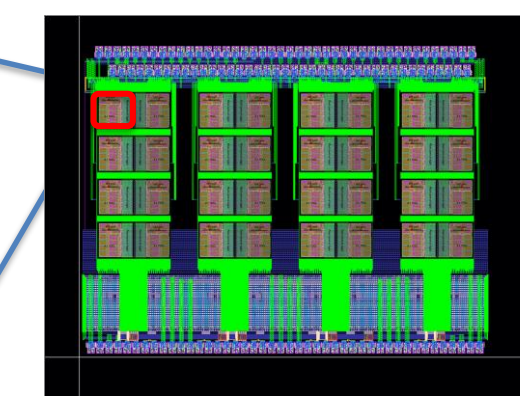
- ALCOR (A Low-power Chip for Optical sensor Readout):



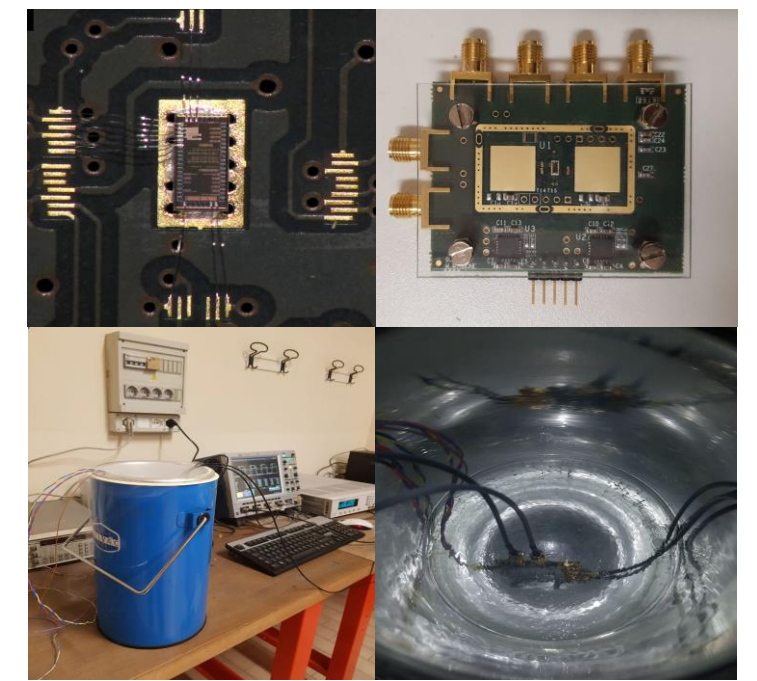
Pixel architecture



Pixel layout constraints



Layout of full chip (Pixels 4 x 8)

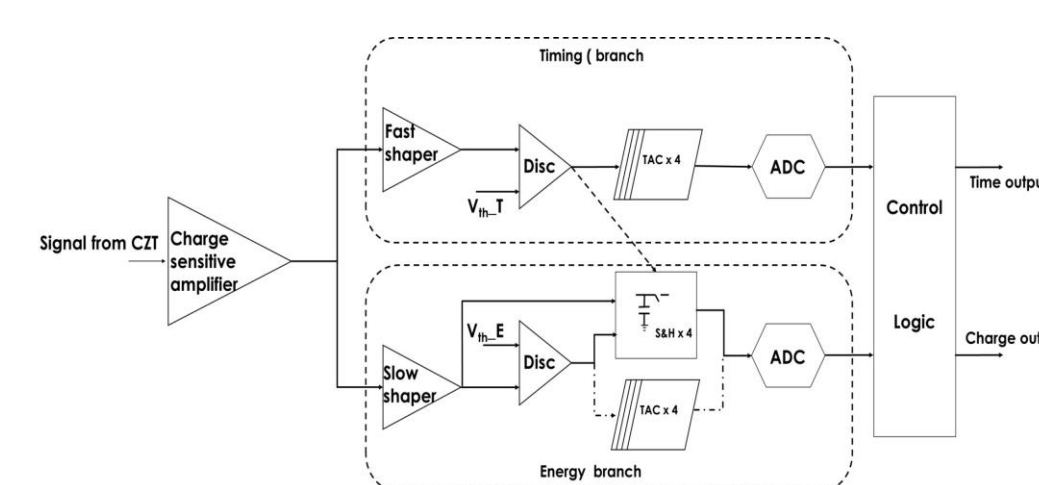


Test chip studied in liquid nitrogen

- Low power high bandwidth pre-amplifier
- Configured to read out positive or negative signals
- 4 gains selectable for each output stage
- Dual thresholds for dark count rejection
- 4 TDCs for de-randomization
- Time over threshold (ToT) provides energy information
- Injection circuit provides test pulse

□ Tape-out in October 2019

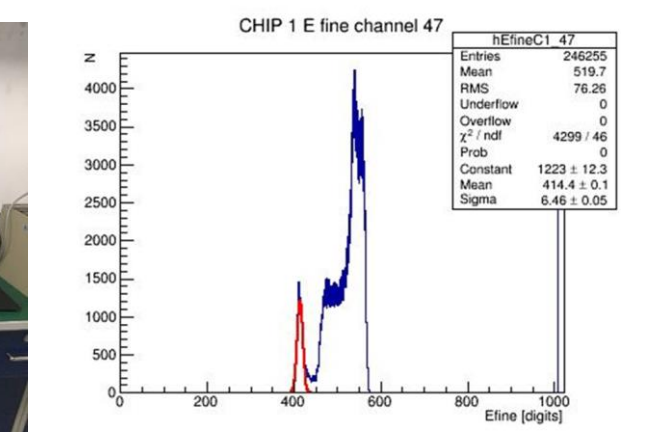
- CZT detector read out ASIC:



One channel architecture



Test environment and result with TIGER ASIC (Radiation source: Cs¹³⁷, with energy resolution of about 5%)



- Share the scheme with **TIGER** (Turin Integrated GEM Electronics Readout, front-end ASIC for CGEM detector in BESIII experiment)
- Time stamp extracted from fast branch, energy from slow branch
- Low power TDCs and ADCs
- 64 channels integrated in one chip
- Low noise front-end: Charge Sensitive Amplifier (CSA) + shapers optimized for CZT detector capacitance, dark current and count rate
- Lower power dissipation
- Adjustable gain and shaping time

□ Tape-out in June 2020

Future work

- ALCOR tape-out and electrical characterization, test with aimed SiPMs
- CZT readout ASIC tape-out and electrical characterization, test with aimed CZT sensors.

List of attended classes

- 02RHORV The new Internet Society: entering the black-box of digital innovations (6 hours, 19/12/2018)
- 01LCPIU Experimental modeling: costruzione di modelli da dati sperimentali (33 hours, 29/10/2018)
- 08IXTRV Project management (5 hours, 19/12/2018)
- 03QRHRV Microelectronics for radiation detection II (24 hours, 3/6/2019)
- 01SYBRV Research integrity (5 hours, 28/1/2019)
- 01SWQRV Responsible research and innovation, the impact on social challenges (5 hours, 26/8/2019)